MEMS Prototyping

In addition to ICs, Circuits Multi Projets®/Multi-Project Circuits® (CMP) is providing MEMS technologies for prototyping and low volume production:

Specific MEMS technologies

These technologies allow the realization of various MEMS devices. $3,700 1cm x 1cm.

Bulk Micromachining

Frontside Bulk Micromachining

ams 0.35μ processes
650€/mm² + 3,700€

Process cross section

Backside Bulk Micromachining

ams 0.35μ processes
 Pricing on request.

On-chip suspended membrane with piezoresistors

Ceramic: CQFP, DIL, LCC, JLC, PGA, SOIC, QFN...
Plastic: BGA, QFN, QFP, PLCC, SOIC, TSOP
Flip Chip and stacked chip Wafer and die thinning

MEMS Packaging:
Optical resin/ Chip On Board (COB) /Thermal solutions/ Metallic package/Hermetic package.

Prices and data are subject to modification at any time, check on web site.